



Docket No. MAIKP131US

J.T.W.
IT601US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

above PATENT application of:

Applicant: Teng-Wang Huang et al.
Application No.: 10/814,570
For: PROCESS FOR ETCHING A SUBSTRATE
Filing Date: March 31, 2004
Examiner: Duy-Vu Nguyen Deo
Art Unit: 1765

RESPONSE TO OFFICE ACTION DATED OCTOBER 30, 2006

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir or Madam:

Favorable reconsideration of the above-identified application is respectfully requested in view of the following amendments and remarks.